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Microscale Heat and Mass Transfer: Materials, Process, and Applications

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Deadline for manuscript submissions: closed (20 February 2023)

Message from the Guest Editor

Rapid increases in heat fluxes within small areas in microelectronic, defense, energy, solar and medical components have prompted an urgent need for microscale heat and mass transfer. These areas have attracted widespread research interest in the last three to four decades. Nevertheless, underlying problems in the selection, design and fabrication of materials pose severe challenges for practical applications of microscale heat and mass transfer in high heat flux dissipations. To address the above mentioned issue, numerous efforts have been made in terms of the design and fabrication of microscale heat and mass transfer devices, and significant enhancement in microscale heat and mass transfer has been achieved. This Special Issue aims to provide a collection of the latest research and findings in the selection, design and fabrication of materials for use in microscale heat and mass transfer









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Message from the Editor-in-Chief

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